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**Listing of Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1.(currently amended) A deposition baffle for protecting a dielectric window in a plasma processing chamber while facilitating inductive coupling of RF energy from a coil outside of the window, through the window and baffle, and into a plasma within the chamber, comprising:

an electrically conductive body having a window side and a plasma side;  
the body having plurality of slots extending therethrough between the sides thereof;

the slots having walls defined by surfaces of the body and are configured to block line-of-sight paths through the body for particles in the chamber moving from the plasma side of the body to the window side of the body;

a plurality of the slots each having an electrically conductive structural element therein fixed to the body between opposite surfaces thereof on substantially only one of said sides of the body; **[[and]]**

the elements having connections to the body distributed on the baffle so as to improve the uniformity of the distribution of power coupled into the plasma through the baffle without limiting the effectiveness of inductive coupling through the baffle; and

the elements being electrically conductive bridges electrically interconnecting opposite walls of the slots on the plasma side of the body, thereby interrupting the slots on the plasma side of the body.

2. (original) The baffle of claim 1 wherein:

the slots have chevron-shaped cross sections.

Claims 3-6 (canceled)